

产品规格承认书

SPECIFICATIONS

客户:

CUSTOMER: _____

产品名称:

DESCRIPTION: Ceramic Antenna

客户型号:

CUSTOMER PART No: _____

产品型号:

OUR MODEL NO: **PBX3216DA01**

日期:

DATE: _____

确认签字, 盖章后请返回承认书一份

PLEASE RETRUV TO US ONE COPY OF "SPECIFICATION FOR APPROVAL"

WITY YOUR APPROVED SIGNATURES

Approved	LiuFei	Audit	LiuFei	Making	LiuXiaoMei
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Customer Acknowledges Signature	
Date	

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TITLE: CHIP2450-3216 Specification		DOCUMENT NO. 3216
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PBX3216DA01 Specification

Operating Temp. : -40°C~+85°C

1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

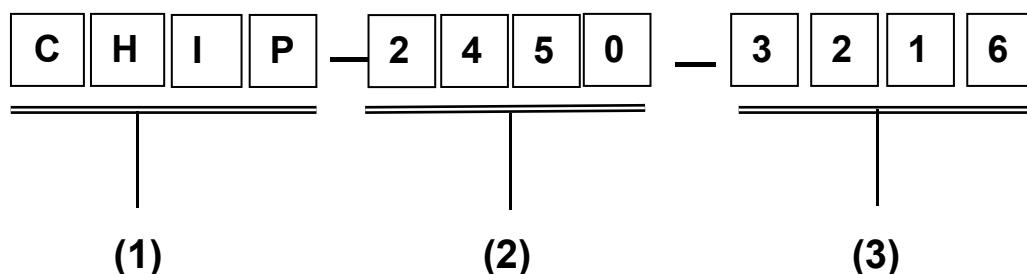


2. APPLICATIONS:

- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

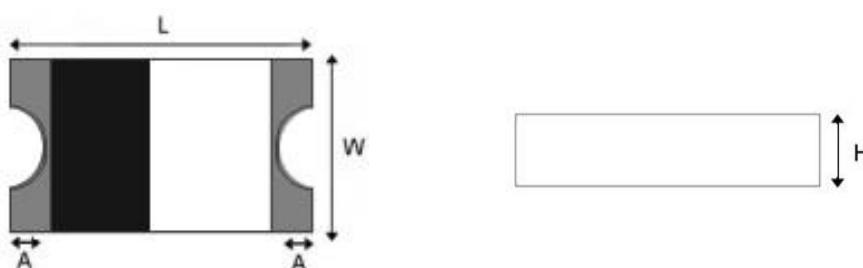


3. PRODUCT IDENTIFICATION



- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 3.2*1.6

4. SHAPE AND DIMENSIONS:



L	W	H	A
3.2 \pm 0.2	1.6 \pm 0.2	0.75 \pm 0.1	0.4 \pm 0.1

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NO**

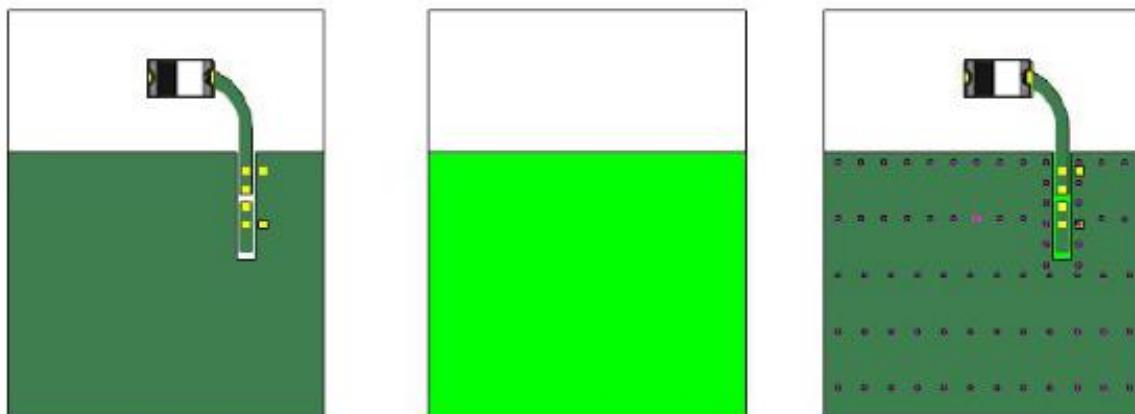
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Test plate reference size: (Note: Please Point the white end of the antenna towards the chip)

Company: mm

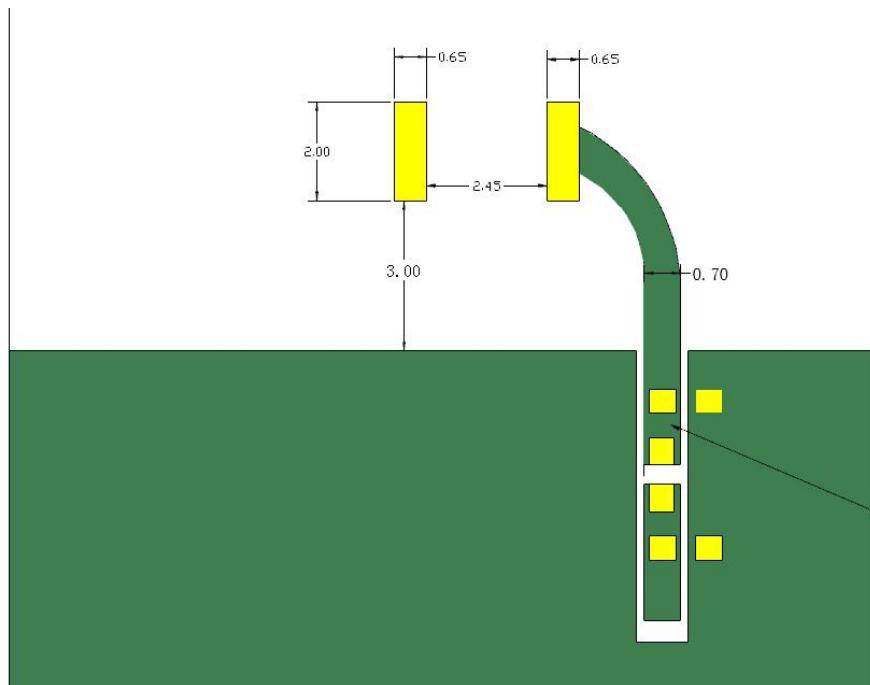


Top layer copper laying

Pad

Copper laying on the bottom layer

Punch



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ANGLES = \pm **HOLE DIA** = \pm



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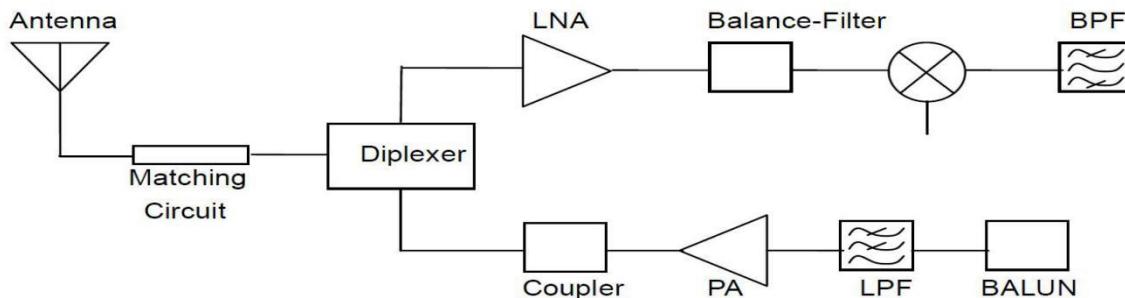
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APPLICATION GUIDE**5. SPECIFICATIONS:**

No.	Product number	PBX3216DA01	
1	Central Frequency	2440	MHz
2	Bandwidth	100 (Min.)	MHz
3	Return Loss	-11.96 (Max.)	dB
4	Peak Gain	2.7	dBi
5	Impedance	50	Ω
6	Operating Temperature	-40~+85	°C
7	Maximum Power	5	W
8	Resistance to soldering heat	10 (@260°C)	Sec.
9	Polarization	Linear	
10	Azimuth Beam width	Omni-directional	
11	Termination	Sn (leadless)	

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6. Electrical Characteristics :



Frequency (MHz)	2400	2450	2500
Avg. Gain (dBi)	-1.83	-1.86	-2.97
Peck Gain (dBi)	2.7	2.58	1.34
Efficiency (%)	65.5	65.22	50.45

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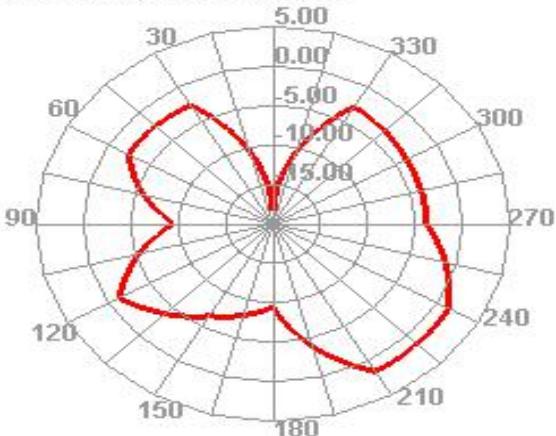
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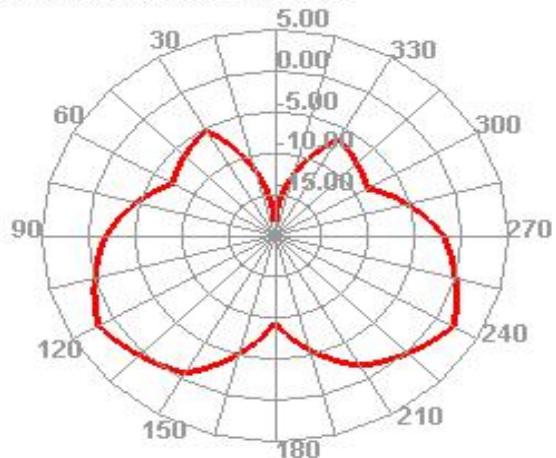
X-Y Plane

2450.000MHz E1



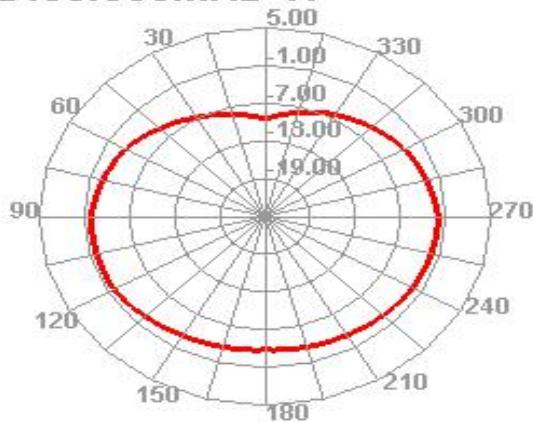
X-Y Plane

2450.000MHz E2



X-Y Plane

2450.000MHz H



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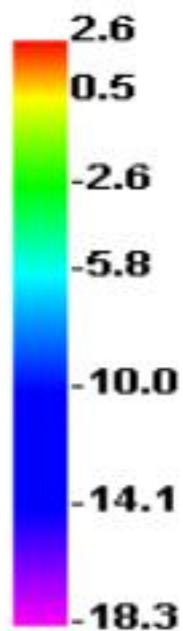
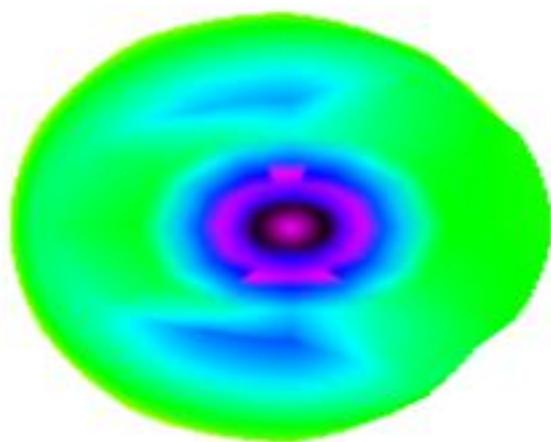
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3D Radiation Pattern

2450.000MHz



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7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at $-40^\circ C \pm 5^\circ C$, 2. Convert to $+105^\circ C$ (5 minutes) 3. 30 ± 3 minutes at $+105^\circ C \pm 5^\circ C$, 4. Convert to $-40^\circ C$ (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85 \pm 5^\circ C$ 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: $150^\circ C \pm 5^\circ C$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: $-40^\circ C \pm 5^\circ C$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : $260 \pm 5^\circ C$ 2. Bathing time: 10 ± 1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245 \pm 5^\circ C$ for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^\circ C$ and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

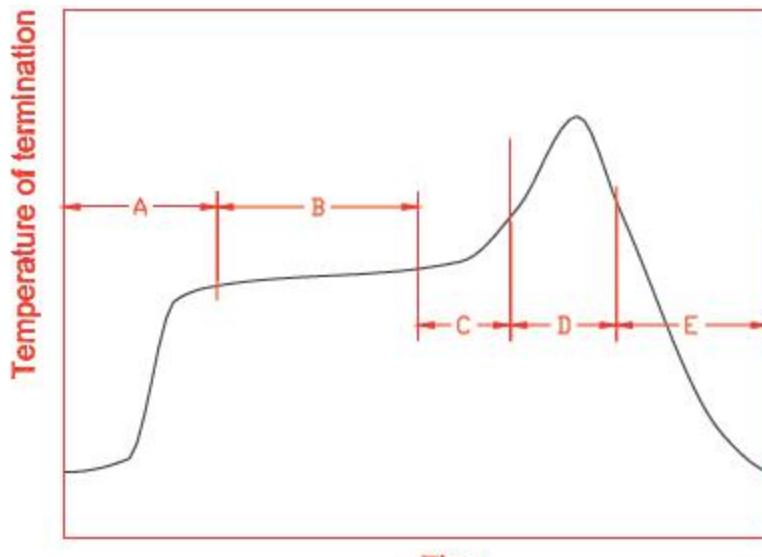
The temperature should be within $-40 \sim 85^\circ C$ and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : $-40^\circ C$ to $+105^\circ C$.

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8. Recommended Reflow Soldering



		Time	
A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- (a) The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

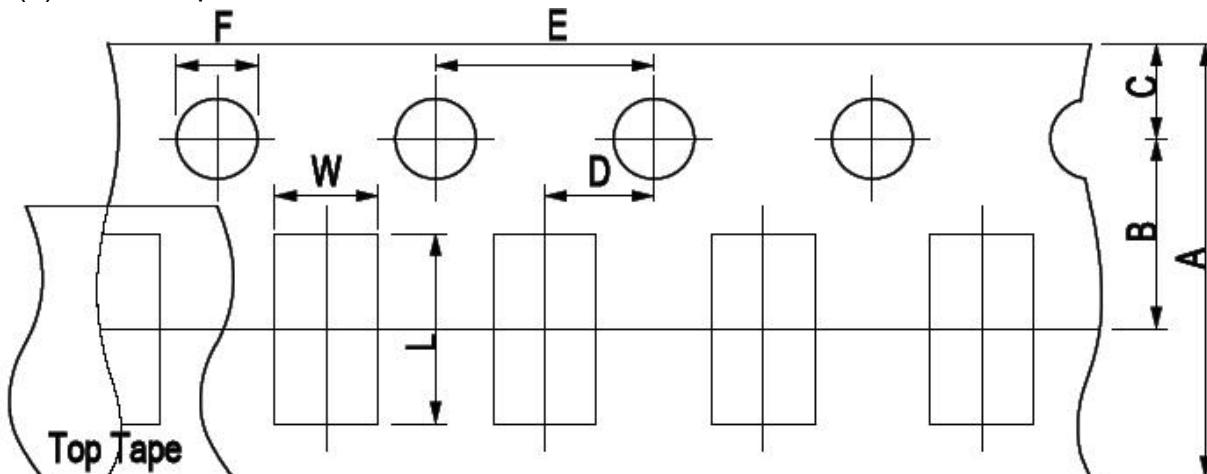
Note that excess of soldering volume will easily get crack the body of this product.

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9. Taping Package and Label Marking: (unit: mm)

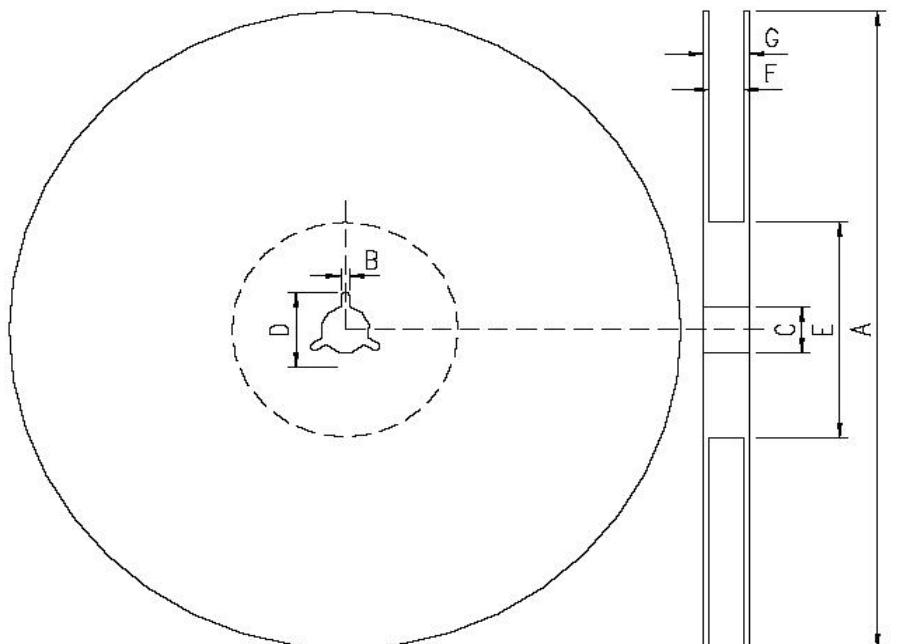
(1) Quantity/Reel: 5000pcs/Reel

(2) Carrier tape dimensions



Type	A	B	C	D	E	F	L	W
2450-21	8.00 ± 0.3	3.50 ± 0.05	1.75 ± 0.1	2.00 ± 0.05	4.00 ± 0.1	1.50 ± 0.1	2.30 ± 0.1	1.55 ± 0.1

(3) Taping reel dimensions



A	178.0 ± 2.0
B	2.0 ± 0.5
C	13.0 ± 0.5
D	21.0 ± 0.8
E	62.0 ± 1.5
F	9.0 ± 0.5
G	13.0 ± 1.0

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ANGLES $= \pm$ **HOLE DIA** $= \pm$

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